

WHAT IS CLAIMED IS:

- 1 1. A chip device comprising:
2 a leadframe including a plurality of leads;
3 a die including a metallized backside and further including source and gate
4 terminals opposite the metallized backside, the die being coupled to the leadframe such
5 that the leads of the leadframe are directly coupled to the terminals; and
6 a body with a window defined therein, the body enveloping at least a
7 portion of the leadframe and the die;
8 wherein the die is positioned with respect to the body such that the
9 metallized backside is adjacent the window.
- 1 2. A chip device in accordance with claim 1 wherein the die is
2 coupled to the leadframe with solder bumps.
- 1 3. A chip device in accordance with claim 1 wherein the leadframe is
2 silver plated where the leadframe is coupled to the terminals.
- 1 4. A chip device in accordance with claim 1 wherein the leadframe is
2 nickel plated where the leadframe is coupled to the terminals.
- 1 5. A chip device in accordance with claim 1 wherein the device
2 comprises two dies each including a metallized backside and each further including
3 source and gate terminals opposite the metallized backside, the dies being coupled to
4 corresponding die attach pads of the leadframe such that the leads of the leadframe are
5 directly coupled to the terminals, and wherein the body includes two windows defined
6 therein and the dies are positioned with respect to the body such that the metallized
7 backsides are adjacent a corresponding window.
- 1 6. A chip device in accordance with claim 5 wherein the die attach
2 pads are coupled to one another.
- 1 7. A method of making a chip device, the method comprising:
2 providing a leadframe that includes leads;

3 providing a die that includes a metallized backside;
4 coupling the die to the leadframe; and
5 encapsulating the die with a body such that the metallized backside of the
6 die is adjacent a window defined within the body.

1 8. A method in accordance with claim 7 further comprising
2 configuring the plurality of leads.

1 9. A method in accordance with claim 8 further comprising removing
2 dambars from the leadframe, removing mold flashes and resins from the leads, and solder
3 plating the leads.

1 10. A method in accordance with claim 7 further comprising marking
2 the body on a surface opposite the window.

1 11. A method in accordance with claim 10 wherein the marking is
2 performed with a laser.

1 12. A method in accordance with claim 10 wherein the marking is
2 performed with ink.

1 13. A method in accordance with claim 7 wherein the leadframe is
2 provided with preplated leads.

1 14. A method in accordance with claim 7 wherein the leadframe is
2 provided with preformed leads.

1 15. A method in accordance with claim 7 wherein the leadframe is
2 provided with preplated leads and preformed leads.

1 16. A method in accordance with claim 7 wherein the die is coupled to
2 the leadframe die attach pad and post via solder bumps, and wherein the solder bumps are
3 re-flowed.

- 1 17. A method in accordance with claim 7 wherein the leadframe is
- 2 provided with two die attach pads and posts, and the method further comprises providing
- 3 two dies that each include a metallized back side, and coupling the first of the two dies to
- 4 a first die attach pad and post, coupling a second of the two dies to a second die attach
- 5 pad and post.